

EMIPAK-1B PressFit Power Module Neutral Point Clamp Topology, 30 A



EMIPAK-1B
(package example)

FEATURES

- Ultrafast Trench IGBT technology
- HEXFRED® and silicon carbide diode technology
- PressFit pins technology
- Exposed Al_2O_3 substrate with low thermal resistance
- Low internal inductances
- UL approved file E78996 
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT

PRODUCT SUMMARY

TRENCH IGBT 1200 V STAGE	
V_{CES}	1200 V
$V_{CE(ON)}$ typical at $I_C = 30$ A	2.12 V
I_C at $T_C = 102$ °C	30 A
TRENCH IGBT 600 V STAGE	
V_{CES}	600 V
$V_{CE(ON)}$ typical at $I_C = 30$ A	1.42 V
I_C at $T_C = 106$ °C	30 A
Speed	8 kHz to 30 kHz
Package	EMIPAK-1B
Circuit	3-levels neutral point clamp topology

DESCRIPTION

VS-ENQ030L120S is an integrated solution for a neutral point clamp topology in a single package. The EMIPAK-1B package is easy to use thanks to the PressFit pins and the exposed substrate provides improved thermal performance.

The optimized layout also helps to minimize stray parameters, allowing for better EMI performance.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Operating junction temperature	T _J		150	°C
Storage temperature range	T _{Stg}		-40 to +150	
RMS isolation voltage	V _{ISOL}	T _J = 25 °C, all terminals shorted, f = 50 Hz, t = 1 s	3500	V
Q1 - Q4 TRENCH IGBT 1200 V				
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V _{GES}		± 30	
Pulsed collector current	I _{CM}		120	A
Clamped inductive load current	I _{LM} ⁽¹⁾		120	
Continuous drain current	I _C	T _C = 25 °C	61	A
		T _C = 80 °C	40	
		T _{SINK} = 80 °C	21	
Power dissipation	P _D	T _C = 25 °C	216	W
		T _C = 80 °C	121	
Q2 - Q3 TRENCH IGBT 600 V				
Collector to emitter voltage	V _{CES}		600	V
Gate to emitter voltage	V _{GES}		± 20	
Pulsed collector current	I _{CM}		130	A
Clamped inductive load current	I _{LM} ⁽²⁾		130	
Continuous collector current	I _C	T _C = 25 °C	64	A
		T _C = 80 °C	42	
		T _{SINK} = 80 °C	25	
Power dissipation	P _D	T _C = 25 °C	174	W
		T _C = 80 °C	97	

**ABSOLUTE MAXIMUM RATINGS****D1 - D4 HEXFRED ANTIPARALLEL DIODE**

Single pulse forward current	I_{FSM}	10 ms sine or 6 ms rectangular pulse, $T_J = 25\text{ }^{\circ}\text{C}$	180	A
Diode continuous forward current	I_F	$T_C = 25\text{ }^{\circ}\text{C}$	46	A
		$T_C = 80\text{ }^{\circ}\text{C}$	30	
		$T_{SINK} = 80\text{ }^{\circ}\text{C}$	17	
Power dissipation	P_D	$T_C = 25\text{ }^{\circ}\text{C}$	187	W
		$T_C = 80\text{ }^{\circ}\text{C}$	105	

D2 - D3 SILICON CARBIDE ANTIPARALLEL DIODE

Single pulse forward current	I_{FSM}	10 ms sine or 6 ms rectangular pulse, $T_J = 25\text{ }^{\circ}\text{C}$	150	A
Diode continuous forward current	I_F	$T_C = 25\text{ }^{\circ}\text{C}$	40	A
		$T_C = 80\text{ }^{\circ}\text{C}$	28	
		$T_{SINK} = 80\text{ }^{\circ}\text{C}$	20	
Power dissipation	P_D	$T_C = 25\text{ }^{\circ}\text{C}$	140	W
		$T_C = 80\text{ }^{\circ}\text{C}$	79	

Notes

- Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur.
- (1) $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 4.7\text{ }\Omega$, $T_J = 150\text{ }^{\circ}\text{C}$
- (2) $V_{CC} = 300\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 4.7\text{ }\Omega$, $T_J = 150\text{ }^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Q1 - Q4 TRENCH IGBT 1200 V						
Collector to emitter breakdown voltage	BV_{CES}	$V_{GE} = 0\text{ V}$, $I_C = 100\text{ }\mu\text{A}$	1200	-	-	V
Collector to emitter voltage	$V_{CE(ON)}$	$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$	-	2.12	2.52	
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	2.31	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$, $I_C = 1.0\text{ mA}$	2.6	4.6	6.6	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$ (25 °C to 125 °C)	-	- 14	-	mV/°C
Forward transconductance	g_{fe}	$V_{CE} = 20\text{ V}$, $I_C = 30\text{ A}$	-	36	-	S
Transfer characteristics	V_{GE}	$V_{CE} = 20\text{ V}$, $I_C = 30\text{ A}$	-	7.1	-	V
Zero gate voltage collector current	I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$	-	0.001	0.23	mA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	0.5	-	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 30\text{ V}$, $V_{CE} = 0\text{ V}$	-	-	± 200	nA
Q2 - Q3 TRENCH IGBT 600 V						
Collector to emitter breakdown voltage	BV_{CES}	$V_{GE} = 0\text{ V}$, $I_C = 150\text{ }\mu\text{A}$	600	-	-	V
Collector to emitter voltage	$V_{CE(ON)}$	$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$	-	1.42	1.87	
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	1.56	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$, $I_C = 1.4\text{ mA}$	3.6	5.6	7.1	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$ (25 °C to 125 °C)	-	-17	-	mV/°C
Forward transconductance	g_{fe}	$V_{CE} = 20\text{ V}$, $I_C = 30\text{ A}$	-	24	-	S
Transfer characteristics	V_{GE}	$V_{CE} = 20\text{ V}$, $I_C = 30\text{ A}$	-	10	-	V
Zero gate voltage collector current	I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 600\text{ V}$	-	0.0003	0.23	mA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 600\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	0.028	-	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 20\text{ V}$, $V_{CE} = 0\text{ V}$	-	-	± 200	nA
D1 - D4 ANTIPARALLEL DIODE						
Forward voltage drop	V_{FM}	$I_F = 20\text{ A}$	-	2.42	3.18	V
		$I_F = 20\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	2.32	-	
D2 - D3 ANTIPARALLEL DIODE						
Forward voltage drop	V_{FM}	$I_F = 20\text{ A}$	-	1.54	1.8	V
		$I_F = 20\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	1.86	-	



SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Q1 - Q4 TRENCH IGBT (WITH FREEWHEELING D1 - D4 ANTIPARALLEL DIODE)							
Total gate charge (turn-on)	Q _g	I _C = 30 A	-	157	-	nC	
Gate to emitter charge (turn-on)	Q _{ge}	V _{CC} = 600 V	-	21	-		
Gate to collector charge (turn-on)	Q _{gc}	V _{GE} = 15 V	-	69	-		
Turn-on switching loss	E _{ON}	I _C = 30 A V _{CC} = 600 V V _{GE} = 15 V R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	0.52	-	mJ	
Turn-off switching loss	E _{OFF}		-	0.9	-		
Total switching loss	E _{TOT}		-	1.42	-		
Turn-on delay time	t _{d(on)}		R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	93	-	ns
Rise time	t _r			-	39	-	
Turn-off delay time	t _{d(off)}			-	133	-	
Fall time	t _f			-	156	-	
Turn-on switching loss	E _{ON}	I _C = 30 A V _{CC} = 600 V V _{GE} = 15 V R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	0.64	-	mJ	
Turn-off switching loss	E _{OFF}		-	1.61	-		
Total switching loss	E _{TOT}			2.24			
Turn-on delay time	t _{d(on)}		R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	93	-	ns
Rise time	t _r			-	39	-	
Turn-off delay time	t _{d(off)}			-	136	-	
Fall time	t _f			-	193	-	
Input capacitance	C _{ies}	V _{GE} = 0 V V _{CC} = 30 V f = 1 MHz	-	3338	-	pF	
Output capacitance	C _{oes}		-	124	-		
Reverse transfer capacitance	C _{res}		-	75	-		
Reverse bias safe operating area	RBSOA	T _J = 150 °C, I _C = 120 A V _{CC} = 600 V, V _P = 1200 V R _g = 4.7 Ω, V _{GE} = 15 V to 0 V	Fullsquare				
Q2 - Q3 TRENCH IGBT (WITH FREEWHEELING EXTERNAL TO-247 DIODE DISCRETE 30ETH06)							
Total gate charge (turn-on)	Q _g	I _C = 48 A	-	95	-	nC	
Gate to emitter charge (turn-on)	Q _{ge}	V _{CC} = 400 V	-	28	-		
Gate to collector charge (turn-on)	Q _{gc}	V _{GE} = 15 V	-	35	-		
Turn-on switching loss	E _{ON}	I _C = 30 A V _{CC} = 300 V V _{GE} = 15 V R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	0.23	-	mJ	
Turn-off switching loss	E _{OFF}		-	0.26	-		
Total switching loss	E _{TOT}		-	0.49	-		
Turn-on delay time	t _{d(on)}		R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	70	-	ns
Rise time	t _r			-	31	-	
Turn-off delay time	t _{d(off)}			-	91	-	
Fall time	t _f			-	87	-	
Turn-on switching loss	E _{ON}	I _C = 30 A V _{CC} = 300 V V _{GE} = 15 V R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	0.33	-	mJ	
Turn-off switching loss	E _{OFF}		-	0.48	-		
Total switching loss	E _{TOT}		-	0.61	-		
Turn-on delay time	t _{d(on)}		R _g = 4.7 Ω L = 500 μH ⁽¹⁾	-	70	-	ns
Rise time	t _r			-	31	-	
Turn-off delay time	t _{d(off)}			-	96	-	
Fall time	t _f			-	117	-	
Input capacitance	C _{ies}	V _{GE} = 0 V V _{CC} = 30 V f = 1 MHz	-	3025	-	pF	
Output capacitance	C _{oes}		-	245	-		
Reverse transfer capacitance	C _{res}		-	90	-		
Reverse bias safe operating area	RBSOA	T _J = 150 °C, I _C = 130 A V _{CC} = 300 V, V _P = 600 V R _g = 4.7 Ω, V _{GE} = 15 V to 0 V	Fullsquare				

**SWITCHING CHARACTERISTICS** ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)**D1 - D4 ANTIPARALLEL DIODE**

Diode reverse recovery time	t_{rr}	$V_R = 400\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$	-	103	-	ns
Diode peak reverse current	I_{rr}		-	16	-	A
Diode recovery charge	Q_{rr}		-	800	-	nC
Diode reverse recovery time	t_{rr}	$V_R = 400\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	135	-	ns
Diode peak reverse current	I_{rr}		-	21	-	A
Diode recovery charge	Q_{rr}		-	1412	-	nC

D2 - D3 ANTIPARALLEL DIODE

Diode reverse recovery time	t_{rr}	$V_R = 200\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$	-	30	-	ns
Diode peak reverse current	I_{rr}		-	4.8	-	A
Diode recovery charge	Q_{rr}		-	73	-	nC
Diode reverse recovery time	t_{rr}	$V_R = 200\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	31	-	ns
Diode peak reverse current	I_{rr}		-	5	-	A
Diode recovery charge	Q_{rr}		-	78	-	nC

Note

(1) Energy losses include "tail" and diode reverse recovery.

INTERNAL NTC - THERMISTOR SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUE	UNITS
Resistance	R_{25}	$T_C = 25\text{ }^{\circ}\text{C}$	5000	Ω
	R_{100}	$T_C = 100\text{ }^{\circ}\text{C}$	$493 \pm 5\%$	
B-value	$B_{25/50}$	$R_2 = R_{25} \exp. [B_{25/50} (1/T_2 - 1/(298.15\text{ K}))]$	$3375 \pm 5\%$	K
Maximum operating temperature			220	$^{\circ}\text{C}$
Dissipation constant			2	mW/ $^{\circ}\text{C}$
Thermal time constant			8	s

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Q1 - Q4 TRENCH IGBT 1200 V - Junction to case thermal resistance (per switch)	R_{thJC}	-	-	0.58	$^{\circ}\text{C}/\text{W}$
Q2 - Q3 TRENCH IGBT 600 V - Junction to case thermal resistance (per switch)		-	-	0.72	
D1 - D4 AP diode - Junction to case thermal resistance (per diode)		-	-	0.67	
D2 - D3 AP diode - Junction to case thermal resistance (per diode)		-	-	0.89	
Q1 - Q4 TRENCH IGBT 1200 V - Case to sink thermal resistance (per switch)	$R_{thCS}^{(1)}$	-	0.75	-	
Q2 - Q3 TRENCH IGBT 600 V - Case to sink thermal resistance (per switch)		-	0.77	-	
D1 - D4 AP diode - Case to sink thermal resistance (per diode)		-	0.78	-	
D2 - D3 AP diode - Case to sink thermal resistance (per diode)		-	0.65	-	
Case to sink thermal resistance (per module)		-	0.1	-	
Mounting torque (M4)		2	-	3	Nm
Weight		-	28	-	g

Note

(1) Mounting surface flat, smooth, and greased

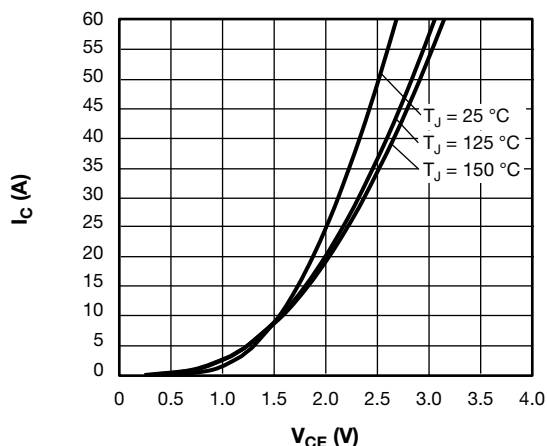


Fig. 1 - Typical Q1 - Q4 Trench IGBT 1200 V Output Characteristics $V_{GE} = 15$ V

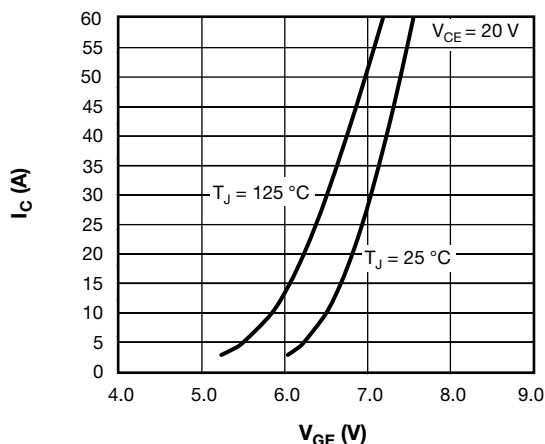


Fig. 4 - Typical Q1 - Q4 Trench IGBT 1200 V Transfer Characteristics

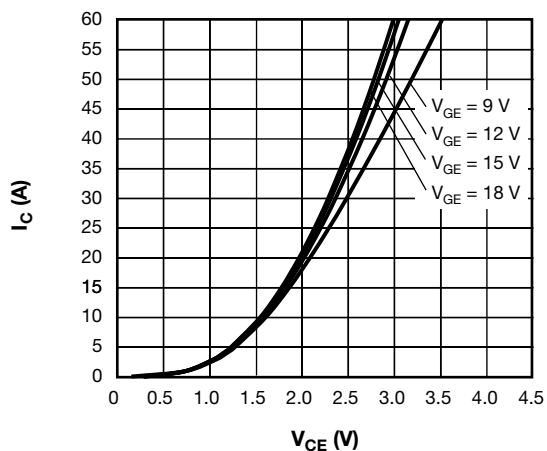


Fig. 2 - Typical Q1 - Q4 Trench IGBT 1200 V Output Characteristics $T_J = 125^\circ\text{C}$

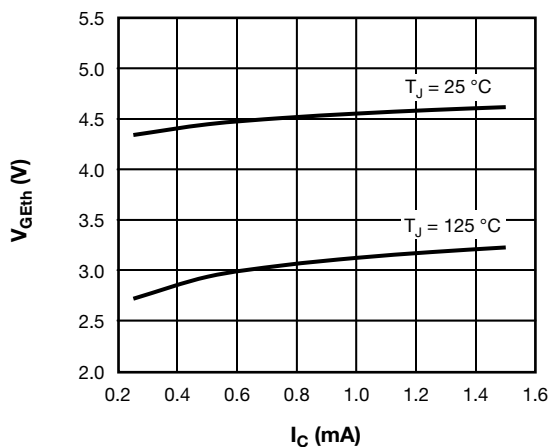


Fig. 5 - Typical Q1 - Q4 Trench IGBT 1200 V Gate Threshold Voltage

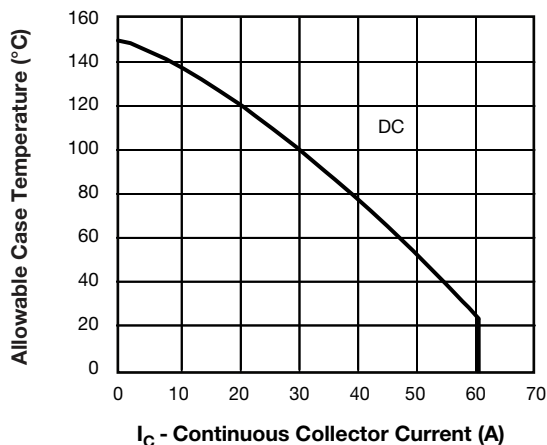


Fig. 3 - Maximum Q1 - Q4 Trench IGBT 1200 V Continuous Collector Current vs. Case Temperature

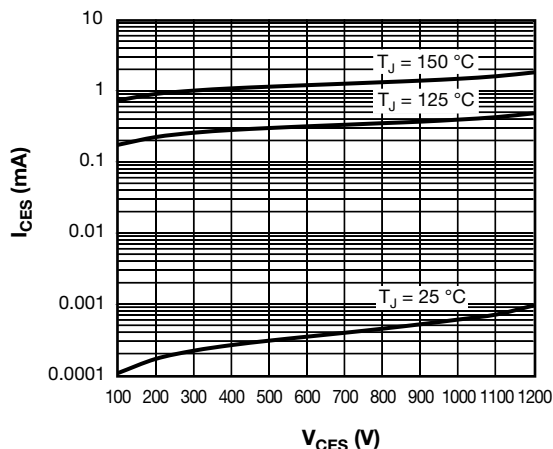


Fig. 6 - Typical Q1 - Q4 Trench IGBT 1200 V Zero Gate Voltage Collector Current

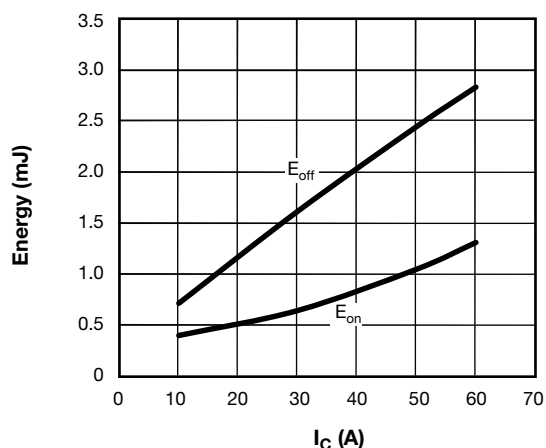


Fig. 7 - Typical Q1 - Q4 Trench IGBT 1200 V
Energy Loss vs. I_C (with D1 - D4 Freewheeling Diode),
 $T_J = 125^\circ\text{C}$, $V_{CC} = 600\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = 15\text{ V}$, $L = 500\ \mu\text{H}$

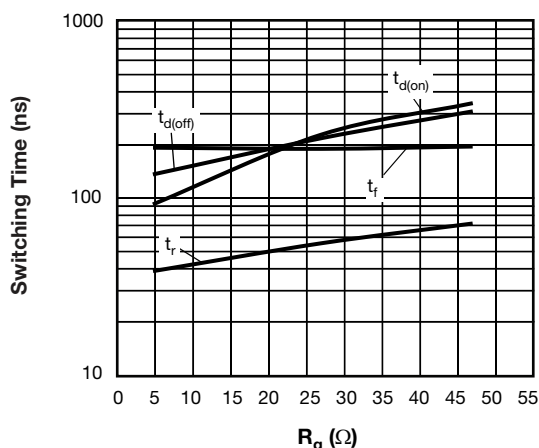


Fig. 10 - Typical Q1 - Q4 Trench IGBT 1200 V
Switching Time vs. R_g (with D1 - D4 Freewheeling Diode)
 $T_J = 125^\circ\text{C}$, $V_{CC} = 600\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\ \mu\text{H}$

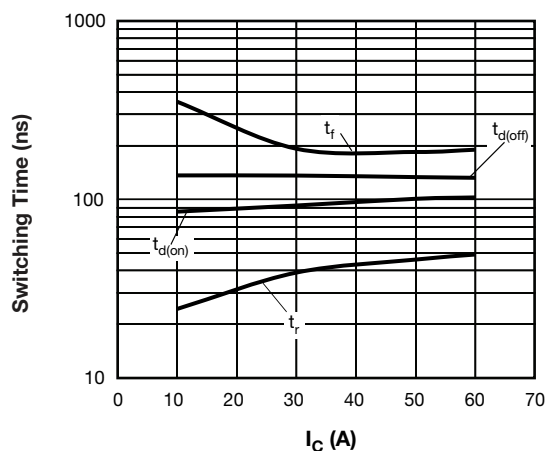


Fig. 8 - Typical Q1 - Q4 Trench IGBT 1200 V
Switching Time vs. I_C (with D1 - D4 Freewheeling Diode)
 $T_J = 125^\circ\text{C}$, $V_{CC} = 600\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = 15\text{ V}$, $L = 500\ \mu\text{H}$

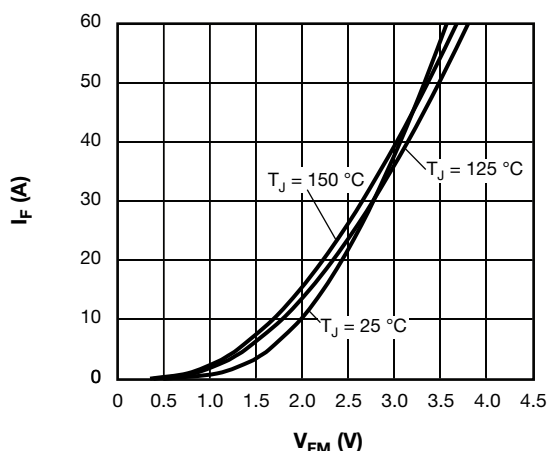


Fig. 11 - Typical D1 - D4 Antiparallel Diode Forward Characteristics

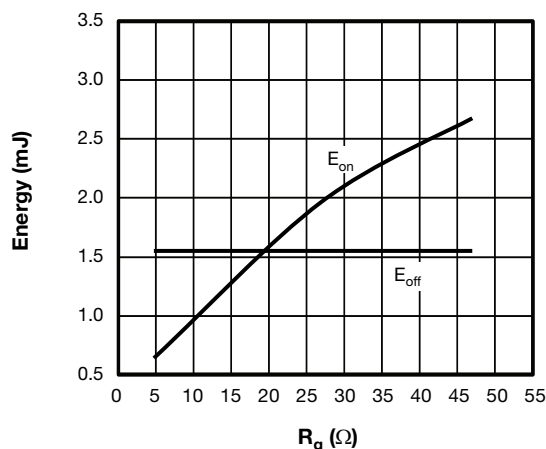


Fig. 9 - Typical Q1 - Q4 Trench IGBT 1200 V
Energy Loss vs. R_g (with D1 - D4 Freewheeling Diode)
 $T_J = 125^\circ\text{C}$, $V_{CC} = 600\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\ \mu\text{H}$

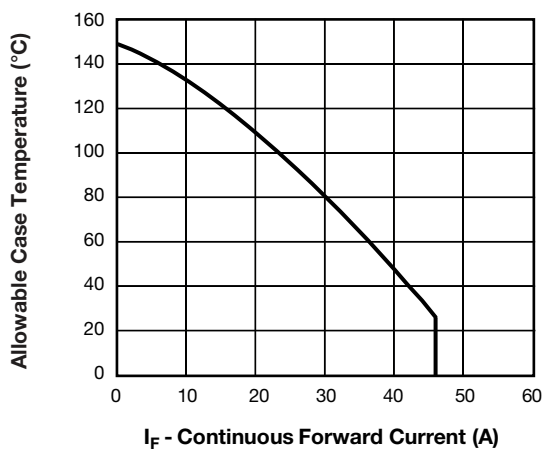


Fig. 12 - Maximum D1 - D4 Antiparallel Diode
Forward Current vs. Case Temperature

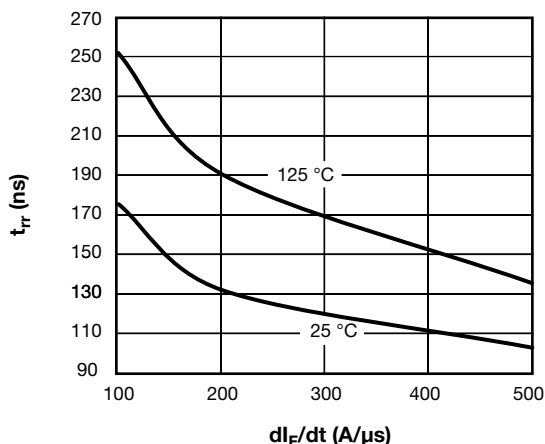


Fig. 13 - Typical D1 - D4 Antiparallel Diode
Reverse Recovery Time vs. dI_F/dt
 $V_{rr} = 400$ V, $I_F = 20$ A

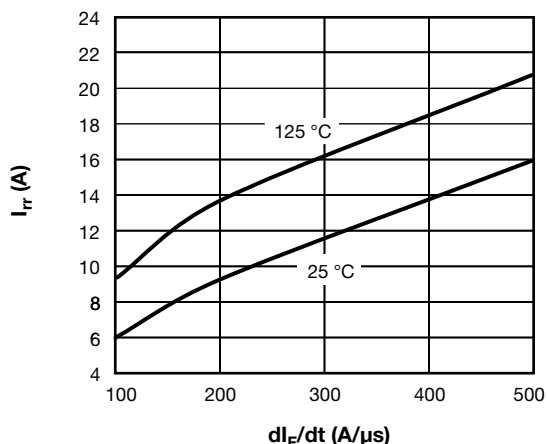


Fig. 14 - Typical D1 - D4 Antiparallel Diode
Reverse Recovery Current vs. dI_F/dt
 $V_{rr} = 400$ V, $I_F = 20$ A

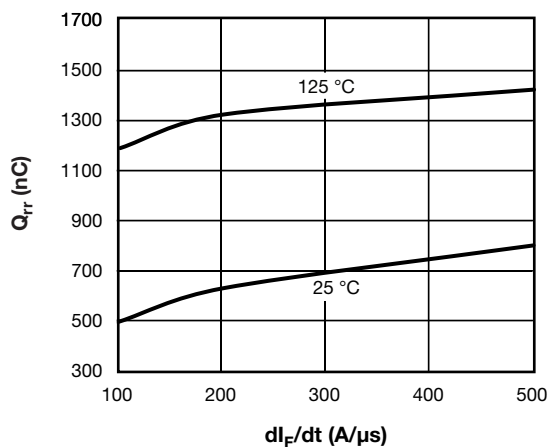


Fig. 15 - Typical D1 - D4 Antiparallel Diode
Reverse Recovery Charge vs. dI_F/dt
 $V_{rr} = 400$ V, $I_F = 20$ A

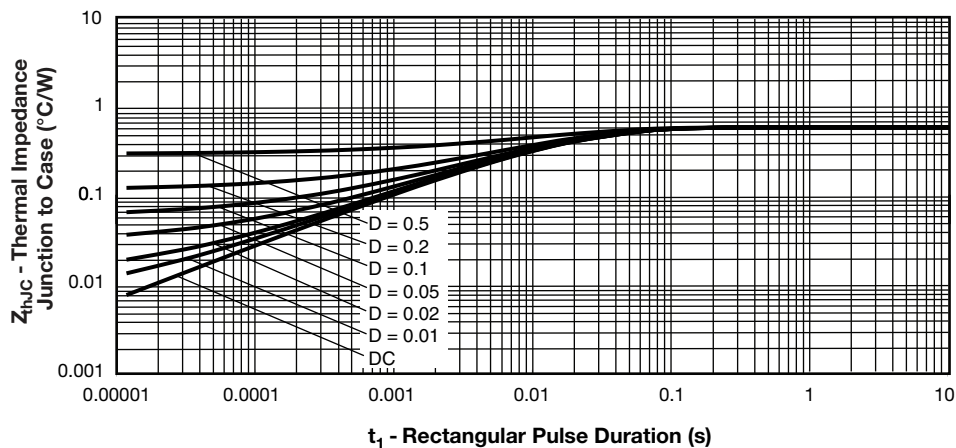


Fig. 16 - Maximum Thermal Impedance Z_{thJC} Characteristics (Q1 - Q4 Trench IGBT 1200 V)

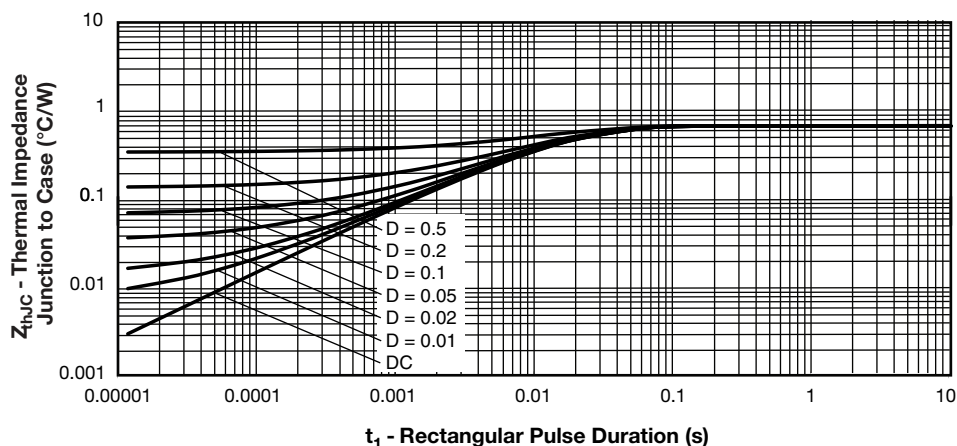


Fig. 17 - Maximum Thermal Impedance Z_{thJC} Characteristics (D1 - D4 Antiparallel Diode)

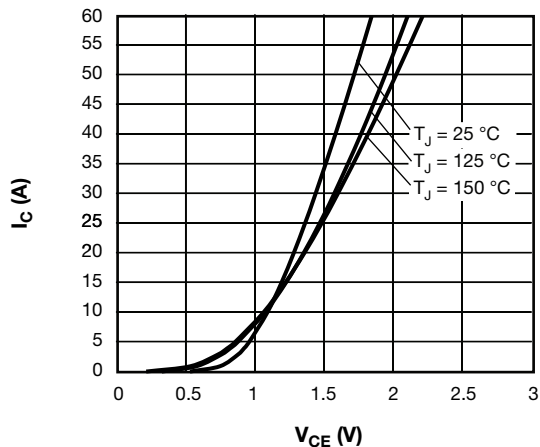


Fig. 18 - Typical Q2 - Q3 Trench IGBT 600 V Output Characteristics
 $V_{GE} = 15 \text{ V}$

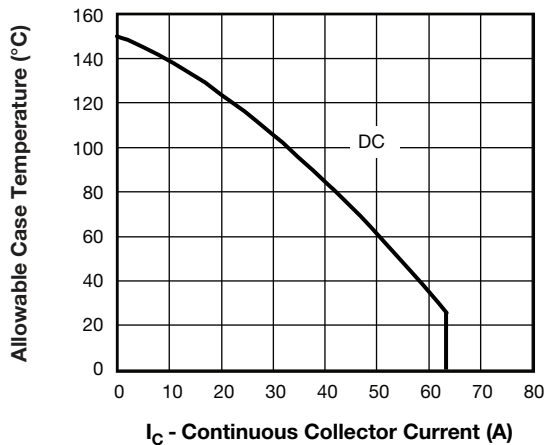


Fig. 20 - Maximum Q2 - Q3 Trench IGBT 600 V Continuous Collector Current vs. Case Temperature

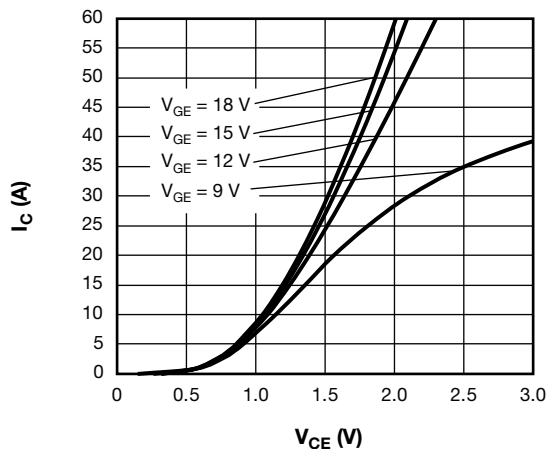


Fig. 19 - Typical Q2 - Q3 Trench IGBT 600 V Output Characteristics
 $T_J = 125 \text{ °C}$

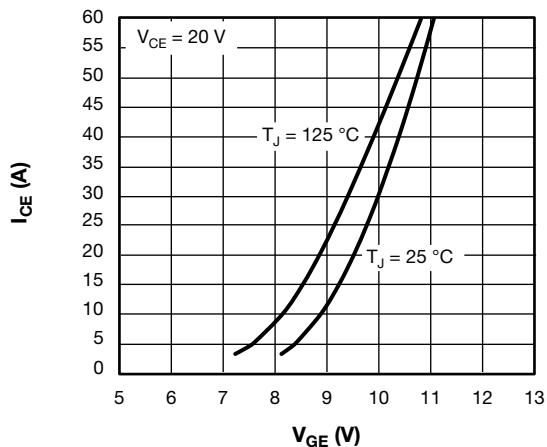


Fig. 21 - Typical Q2 - Q3 Trench IGBT 600 V Transfer Characteristics

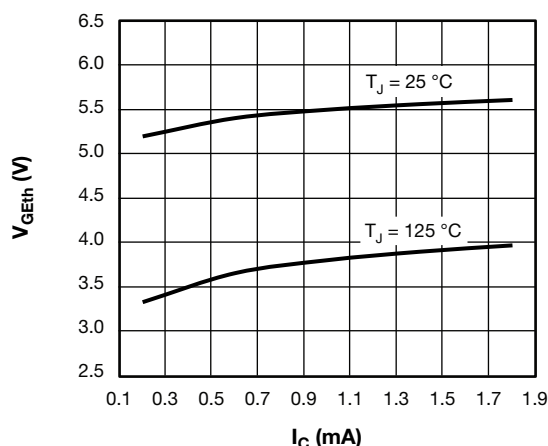


Fig. 22 - Typical Q2 - Q3 Trench IGBT 600 V Gate Threshold Voltage

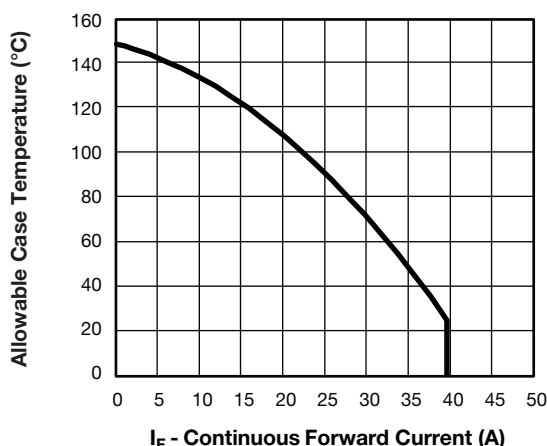


Fig. 25 - Maximum D2 - D3 Antiparallel Diode Forward Current vs. Case Temperature

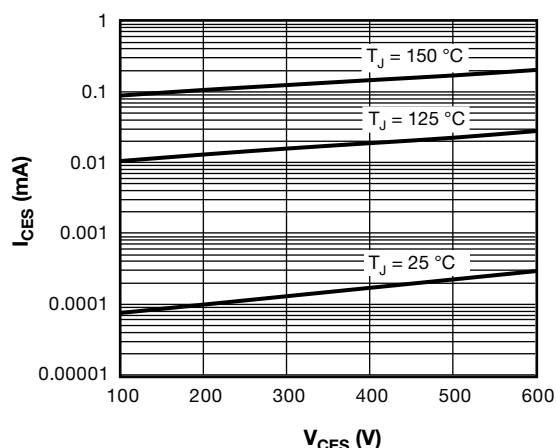


Fig. 23 - Typical Q2 - Q3 Trench IGBT 600 V Zero Gate Voltage Collector Current

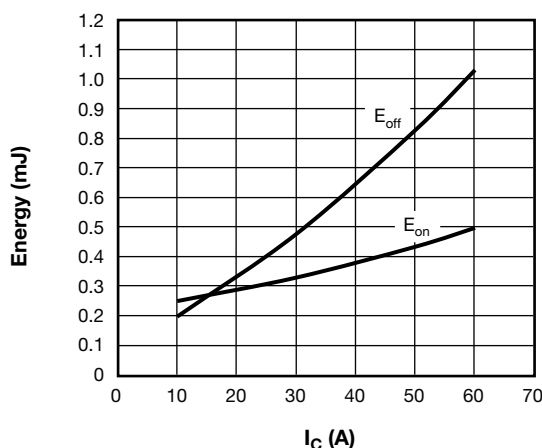


Fig. 26 - Typical Q2 - Q3 Trench IGBT 600 V Energy Loss vs. I_C (with Freewheeling External TO-247 Diode Discrete 30ETH06)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

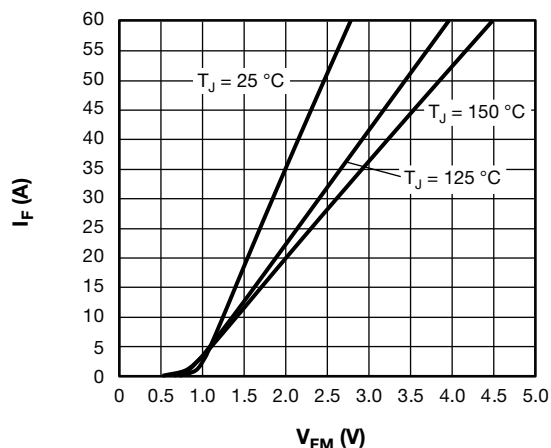


Fig. 24 - Typical D2 - D3 Antiparallel Diode Forward Characteristics

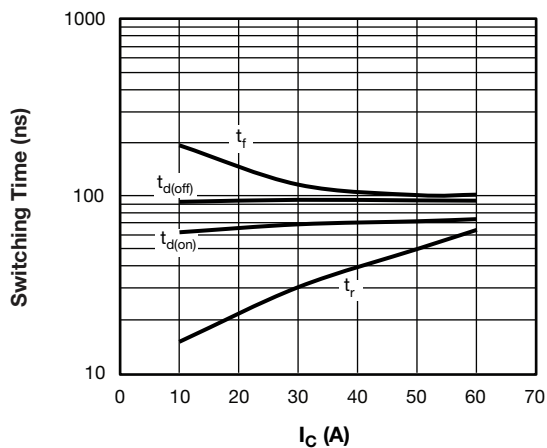


Fig. 27 - Typical Q2 - Q3 Trench IGBT 600 V Switching Time vs. I_C (with Freewheeling External TO-247 Diode Discrete 30ETH06)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

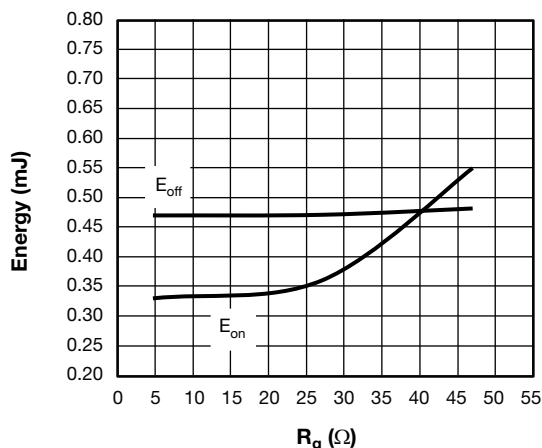


Fig. 28 - Typical Q2 - Q3 Trench IGBT 600 V Energy Loss vs. R_g
(with Freewheeling External TO-247 Diode Discrete 30ETH06)
 $T_J = 125^\circ\text{C}$, $V_{CC} = 300\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

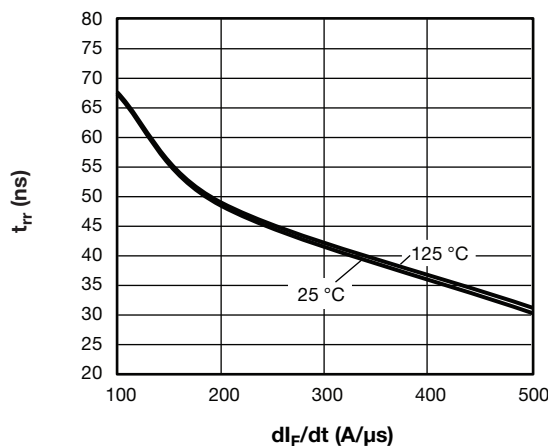


Fig. 30 - Typical D2 - D3 Antiparallel Diode
Reverse Recovery Time vs. dI_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 20\text{ A}$

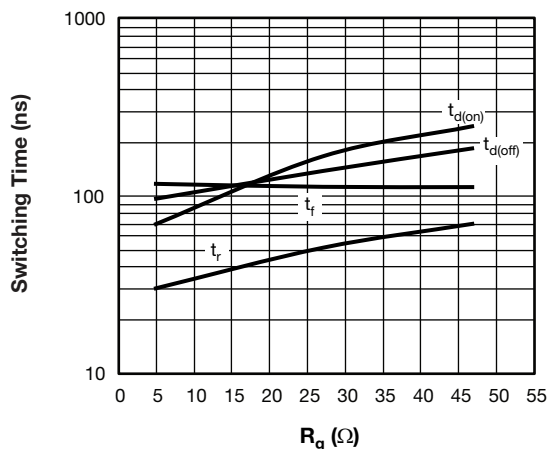


Fig. 29 - Typical Q2 - Q3 Trench IGBT 600 V Switching Time vs. R_g
(with Freewheeling External TO-247 Diode Discrete 30ETH06)
 $T_J = 125^\circ\text{C}$, $V_{CC} = 300\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

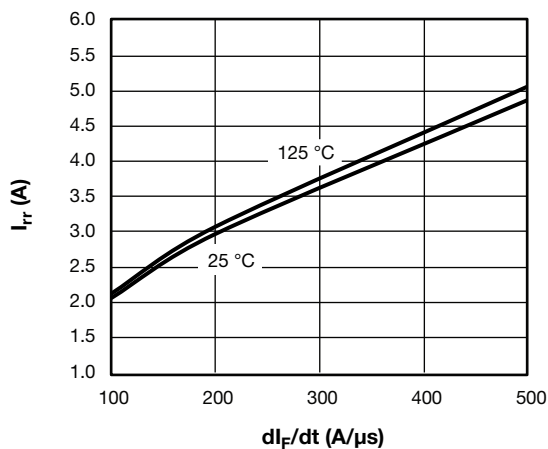


Fig. 31 - Typical D2 - D3 Antiparallel Diode
Reverse Recovery Current vs. dI_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 20\text{ A}$

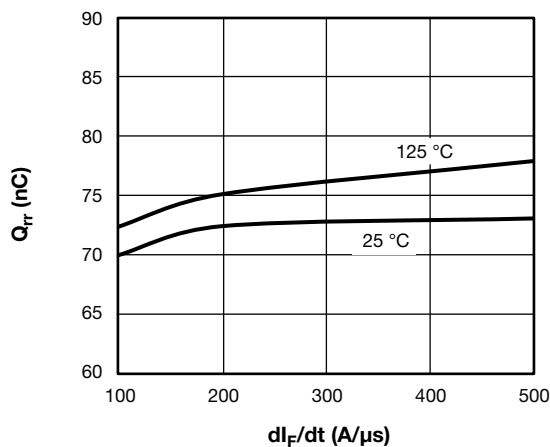


Fig. 32 - Typical D2 - D3 Antiparallel Diode
Reverse Recovery Charge vs. dI_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 20\text{ A}$

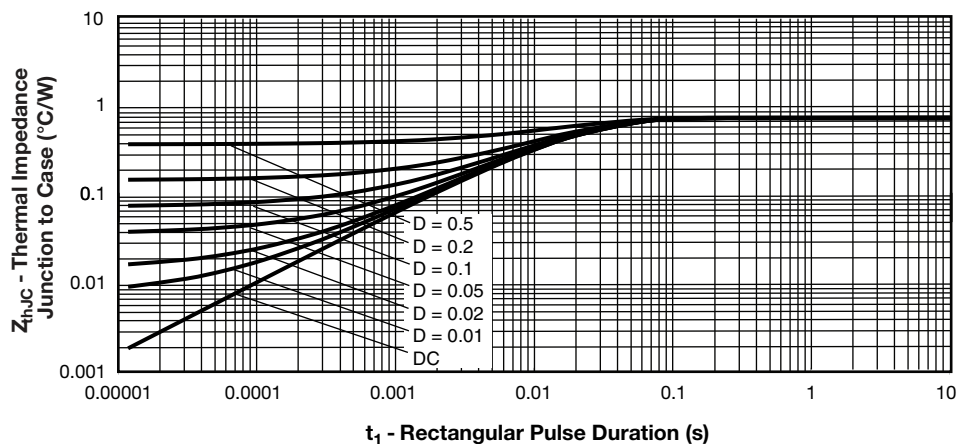


Fig. 33 - Maximum Thermal Impedance Z_{thJC} Characteristics (Q2 - Q3 Trench IGBT 600 V)

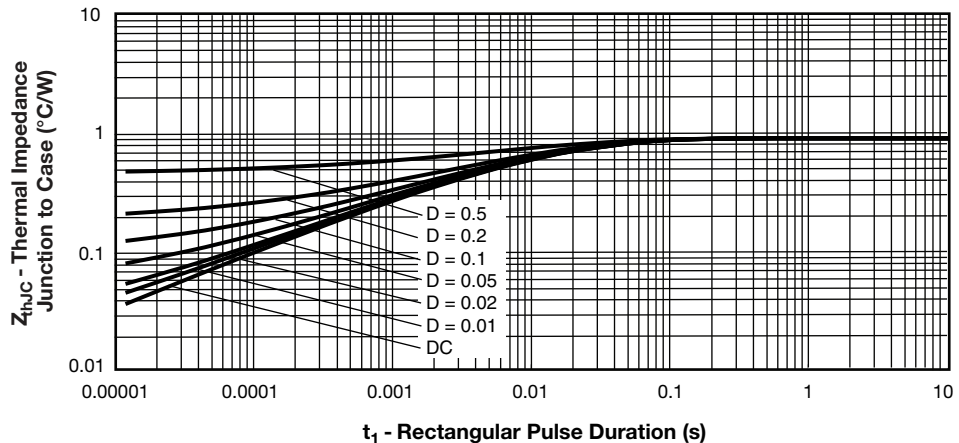


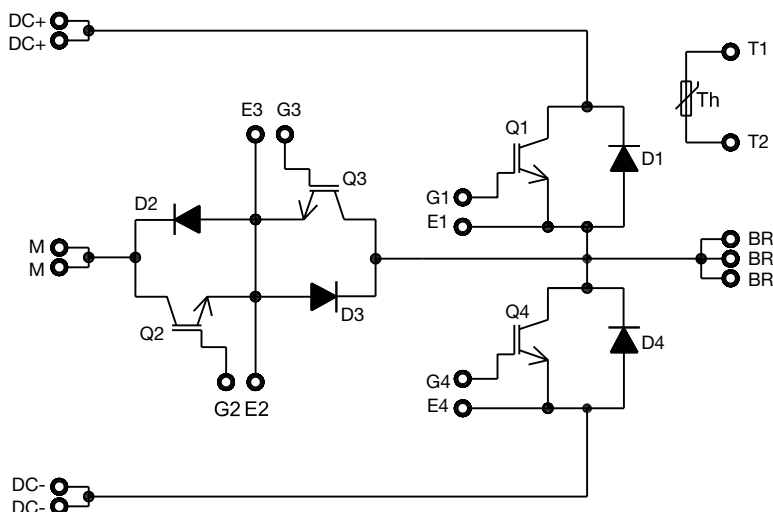
Fig. 34 - Maximum Thermal Impedance Z_{thJC} Characteristics (D2 - D3 Antiparallel Diode)

ORDERING INFORMATION TABLE

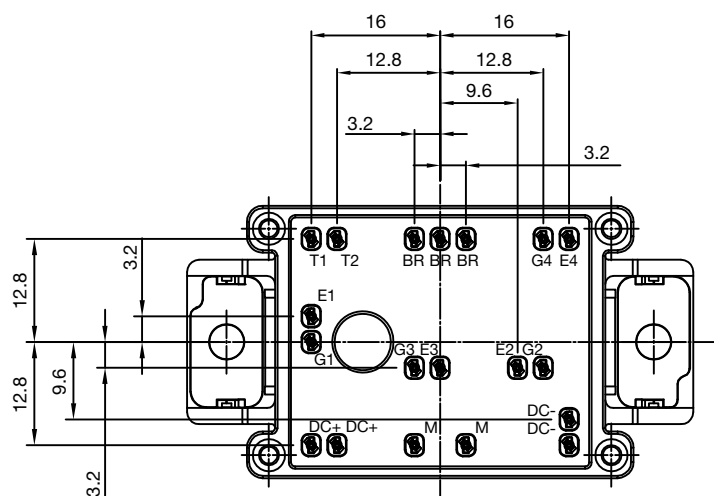
Device code	VS-	EN	Q	030	L	120	S
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - Package indicator (EN = EMIPAK-1B)
- 3** - Circuit configuration (Q = neutral point clamp topology)
- 4** - Current rating (030 = 30 A)
- 5** - Switch die technology (L = ultrafast Trench IGBT 1200 V and Trench IGBT 600 V)
- 6** - Voltage rating (120 = 1200 V)
- 7** - Diode die technology (S = SiC diode)

CIRCUIT CONFIGURATION



PACKAGE

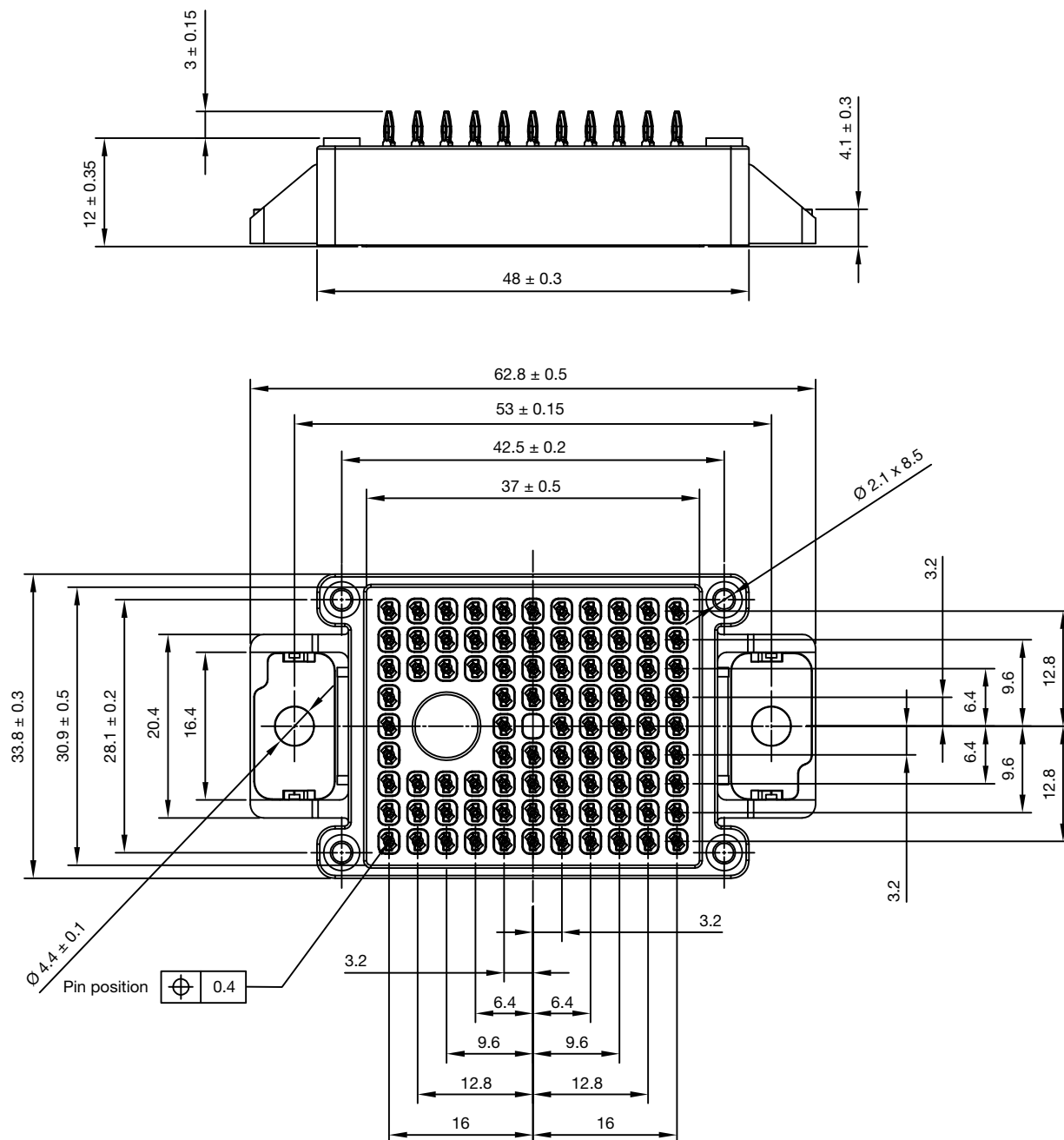


LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95558



EMIPAK-1B PressFit

DIMENSIONS in millimeters





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